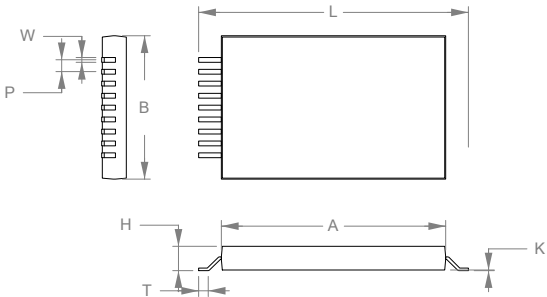


Component (Fig. 1)

Small Outline IC (SOIC)

Pitch.....	1.00
Pin Package.....	18
Pin Count.....	9
Lmin.....	22.60
Lmax.....	22.60
Tmin.....	0.80
Tmax.....	0.80
Wmin.....	0.40
Wmax.....	0.40
Amin.....	18.80
Amax.....	18.80
Bmin.....	12.00
Bmax.....	12.00
Hmax.....	2.04
Kmin.....	0.05

Fig.1



Solder Joint Goals (Fig. 2)

Environment is B - NOMINAL

Toe (Outside) Goal.....	0.35
Toe min.....	0.35
Toe max.....	0.43
Heel (Inside) Goal.....	0.35
Heel Min.....	0.35
Heel max.....	0.43
Side Goal.....	0.03
Side Min.....	0.03
Side max.....	0.10

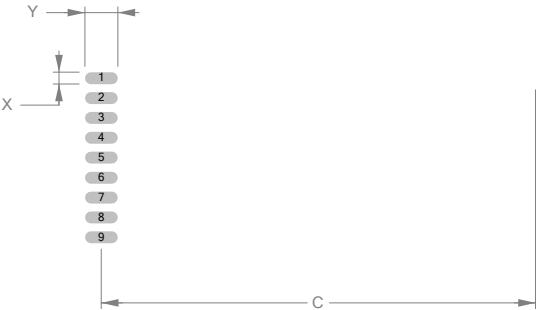
Fig.2



Land Pattern (Fig. 3)

C.....	21.80
Y.....	1.65
X.....	0.60
Pin(s) default	
b165_60	

Fig.3



Silkscreen (Fig. 4)

R1.....19.50
R2.....12.00

Assembly (Fig. 5)

Anom.....18.80
Bnom.....12.00

Courtyard (Fig. 6)

V1.....24.00
V2.....12.50

Program Version: 2010.00.00

Advisories

None

Fig.4

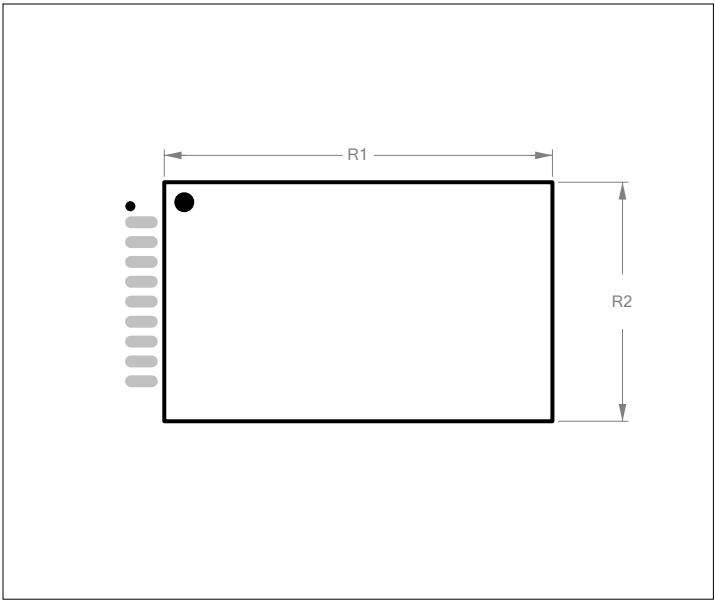


Fig.5

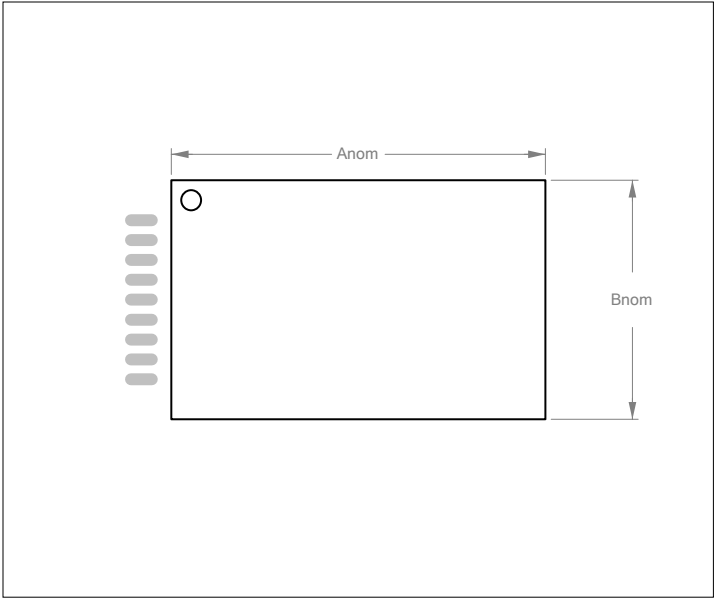


Fig.6

